



DRESDEN 2018



7<sup>th</sup> ELECTRONICS SYSTEM-INTEGRATION TECHNOLOGY CONFERENCE



[www.estc-conference.net](http://www.estc-conference.net)

September 18-20, 2018

## SECOND CALL FOR PAPERS

*THE SINGLE LARGEST SEMICONDUCTOR PACKAGING CONFERENCE IN EUROPE*

It is our pleasure to announce the **7<sup>th</sup> ESTC Conference**, the premier European scientific conference event in the field of microelectronics packaging and system integration.

It will be held **from 18<sup>th</sup> to 20<sup>th</sup> of September, 2018, at the Westin Bellevue Hotel in Dresden, Germany.**

ESTC provides a perfect opportunity to learn about the latest developments in packaging and integration technologies. **Save the date right now!** ESTC is supported by IEEE-EPS in association with IMAPS-Europe.

The **10% best ranked papers** of the conference will be invited to be published as journal publications in IEEE Transactions on Components, Packaging and Manufacturing Technology after the conference.  
**Don't miss this opportunity to place a high ranked journal publication!**



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## CALL FOR PAPERS

ESTC 2018 seeks original papers describing research and innovations in all areas of electronic packaging and system integration. You are invited to submit abstracts that provide non-commercial information of new developments and knowledge in areas like:

- **Advanced packaging**, 3D integration, embedded structures, wafer level packaging, TSVs, TEVs...
- **Materials for interconnects and packaging**, piezoelectric, dielectric and memory materials, nanomaterials...
- **Optoelectronic systems packaging**, fiber optical interconnects, optical sensors, LEDs and other photonic devices...
- **Assembly and manufacturing technologies**, wafer level processing...
- **MEMS/NEMS and sensors packaging**, bonding technologies, wafer bonding, micro-bonding...
- **Design tools and modeling**, thermal, mechanical and electrical modeling, signal and power integrity...
- **Power electronic systems packaging**, power embedding, wide bandgap power semiconductor devices...
- **Advanced technologies for emerging systems**, allotropes of carbon, nano packaging, bio-electronics...
- **Reliability of electronic devices and systems**, characterization and test, failure diagnostic...
- **Flexible printed and hybrid electronics**, printed/jetted conductors, paper electronics, energy storage...

**Special topics:** Automotive, Internet of Things, bio-medical applications

## IMPORTANT DATES

- **Website open for abstract submission: December 1st, 2017**
- **Abstract submission deadline: February 15th, 2018**
- **Notification of acceptance: March 30th, 2018**

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